

General Description

It combines trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

Features

- Low $R_{DS(ON)}$ to minimize conductive loss
- High GOX reliability
- Low Thermal resistance

Application

- BLDC Motor driver
- DC-DC
- Load switch

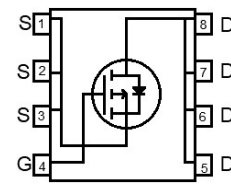
Ordering Information:

Part NO.	ZM240P03M
Marking	240P03
Packing Information	REEL TAPE
Basic ordering unit (pcs)	5000

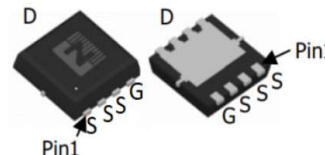
Absolute Maximum Ratings ($T_C=25^\circ\text{C}$)

Parameter	Symbol	Conditions	Value	Unit
Drain-Source Voltage	V_{DS}		-30	V
Gate-Source Voltage	V_{GS}		± 20	V
Continuous Drain Current	I_D	$T_C=25^\circ\text{C}$	-15	A
	I_D	$T_C=75^\circ\text{C}$	-13	A
	I_D	$T_C=100^\circ\text{C}$	-10	A
Pulsed Drain Current	I_{DM}	Pulsed; $t_p \leq 10 \mu\text{s}$; $T_{mb} = 25^\circ\text{C}$;	-60	A
Total Power Dissipation	P_D	$T_C=25^\circ\text{C}$	18	W
Total Power Dissipation	P_D	$T_A=25^\circ\text{C}$	0.9	W
Operating Junction Temperature	T_J		-55 to +150	$^\circ\text{C}$
Storage Temperature	T_{STG}		-55 to +150	$^\circ\text{C}$
Single Pulse Avalanche Energy	E_{AS}	$L=0.1\text{mH}$, $V_{GS}=-10\text{V}$, $R_g=25\Omega$,	45	mJ
		$L=0.5\text{mH}$, $V_{GS}=-10\text{V}$, $R_g=25\Omega$,	95	mJ
ESD Level (HBM)	CLASS 2			

Product Summary



$V_{DS} = -30\text{V}$
 $R_{DS(ON)} = 24\text{m}\Omega$
 $I_D = -15\text{A}$



DFN3*3



•Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}		-	7.1	°C/W
Thermal resistance, junction-ambient ^①	R_{thJA}		-	140	°C/W
Soldering temperature (total time<10s)	Tsold		-	260	°C

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=-250\mu A$	-30			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS}=V_{DS}, I_D=-250\mu A$	-1.2	-1.7	-2.5	V
Drain-Source Leakage Current	I_{DSS}	$V_{GS}=0V, V_{DS}=-30V$			1.0	μA
Gate- Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$			100	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS}=-10V, I_D=-12A$		24	32	m Ω
		$V_{GS}=-4.5V, I_D=-8A$		37	55	m Ω
Forward Transconductance	g_{FS}	$V_{DS}=-5V, I_{SD}=-5A$		18		S
Diode Forward Voltage	V_{FSD}	$V_{GS}=0V, I_{SD}=-12A$			1.3	V

•Dynamic characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Input capacitance	C_{iss}	$f=1MHz, V_{DS}=-25V$	-	960	-	pF
Output capacitance	C_{oss}		-	106	-	
Reverse transfer capacitance	C_{rss}		-	63	-	
Gate Resistance	R_g	$f=1MHz$	-	1.9		Ω
Total gate charge	Q_g	$V_{DD}=-15V, I_D=-12A, V_{GS}=-10V$	-	12	-	nC
	$Q_g(4.5V)$		-	6.5	-	
Gate - Source charge	Q_{gs}		-	2.4	-	
Gate - Drain charge	Q_{gd}		-	2.8	-	
Turn-ON Delay time	$t_{D(on)}$	$V_{GS}=-10V, V_{DS}=-15V, R_G=3.3\Omega, I_D=-20A$	-	10	-	ns
Turn-ON Rise time	t_r		-	15	-	ns
Turn-Off Delay time	$t_{D(off)}$		-	12	-	ns
Turn-Off Fall time	t_f		-	8	-	ns
Reverse Recovery Time	t_{RR}	$V_{DD}=-20V, dI_S/dt=100A/\mu s, I_S=-20A$	-	30	-	ns
Reverse Recovery Charge	Q_{RR}		-	12	-	nC

Fig.1 Gate-Charge Characteristics

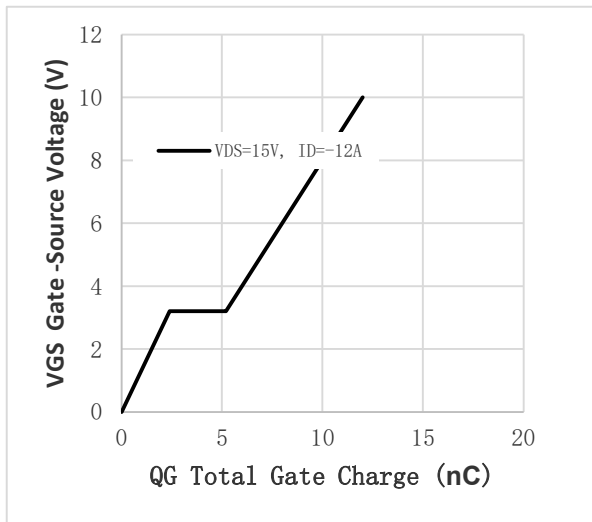


Fig.2 Capacitance Characteristics

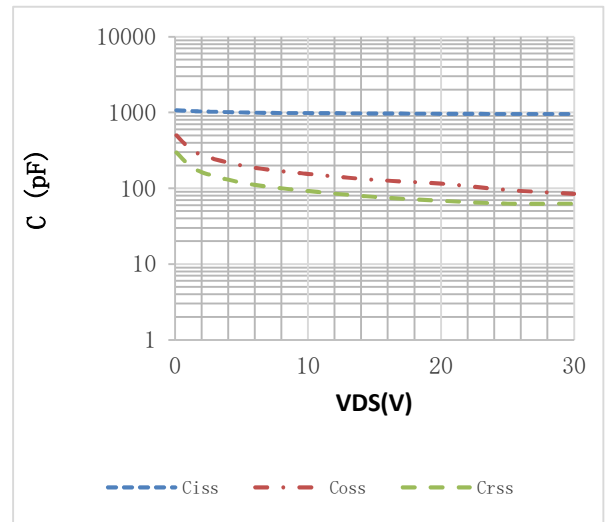


Fig.3 Power Dissipation

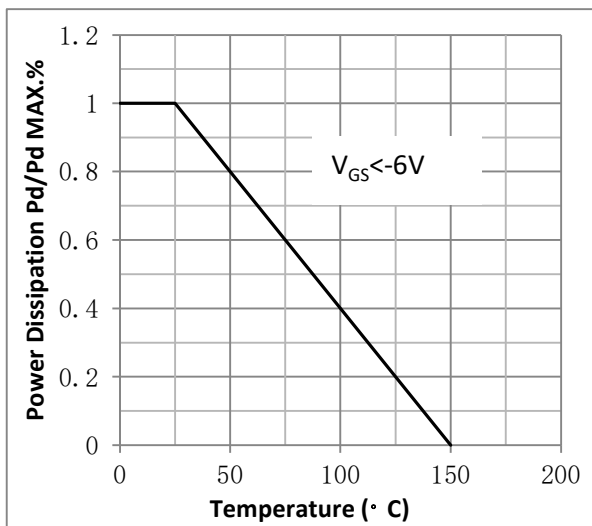


Fig.4 Typical output Characteristics

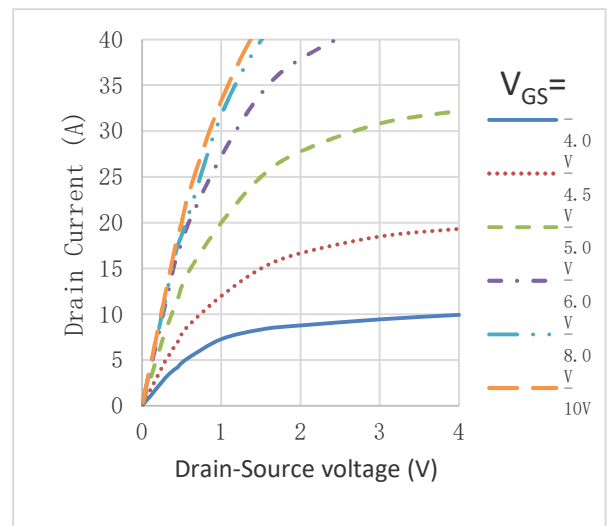


Fig.5 Threshold Voltage V.S Junction Temperature

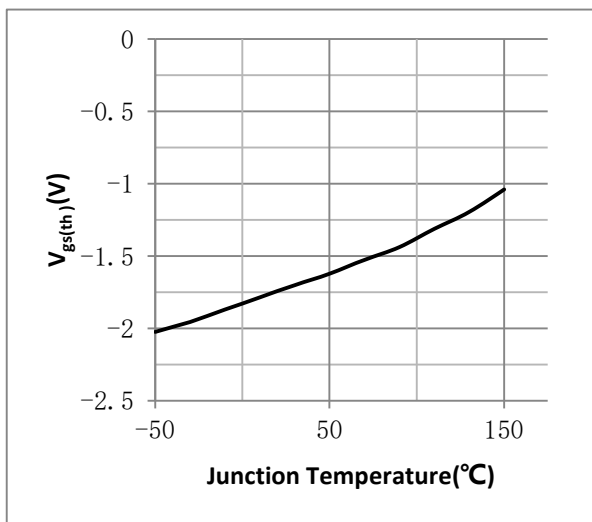


Fig.6 Resistance V.S Drain Current

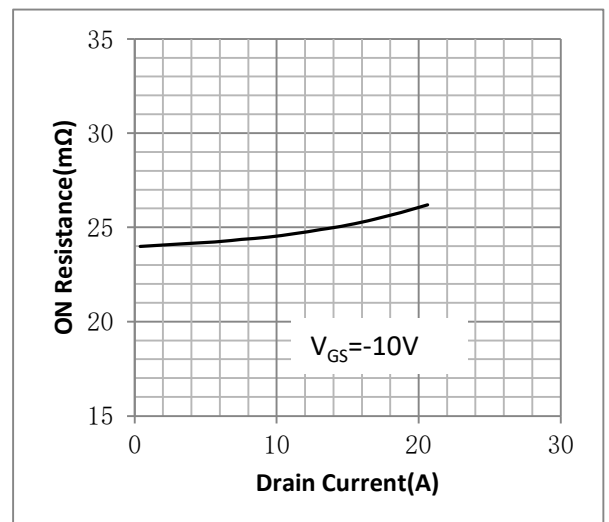


Fig.7 On-Resistance VS Gate Source Voltage

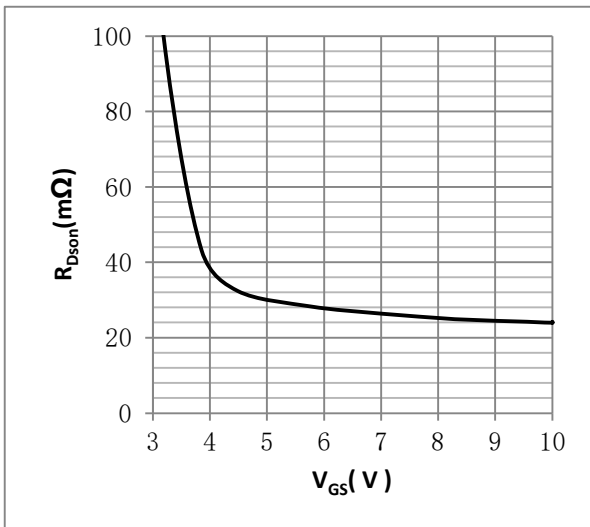


Fig.8 On-Resistance V.S Junction Temperature

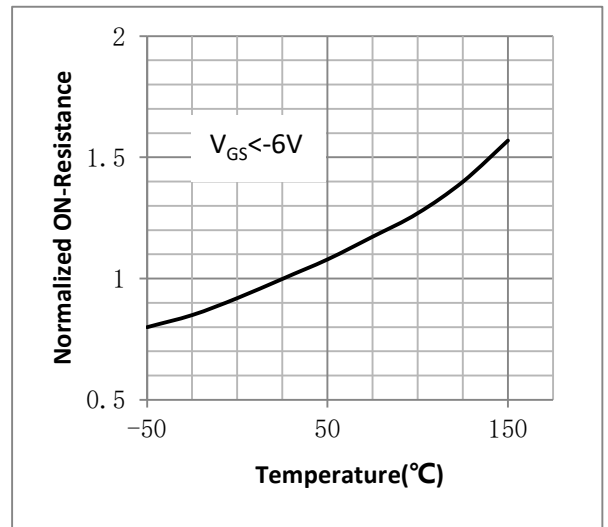


Figure 9. Diode Forward Voltage vs. Current

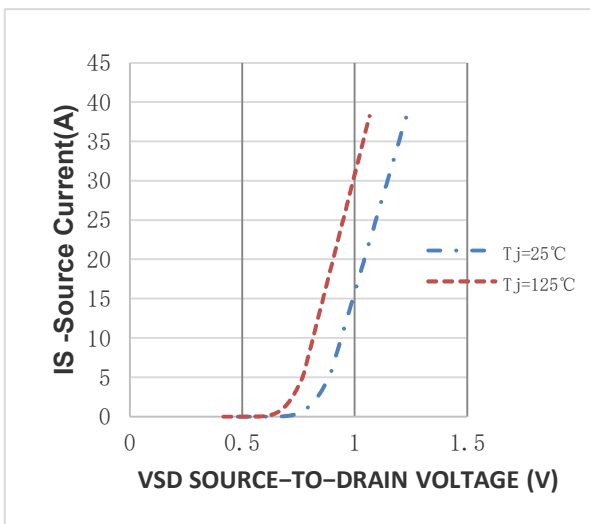


Figure 10. Transfer Characteristics

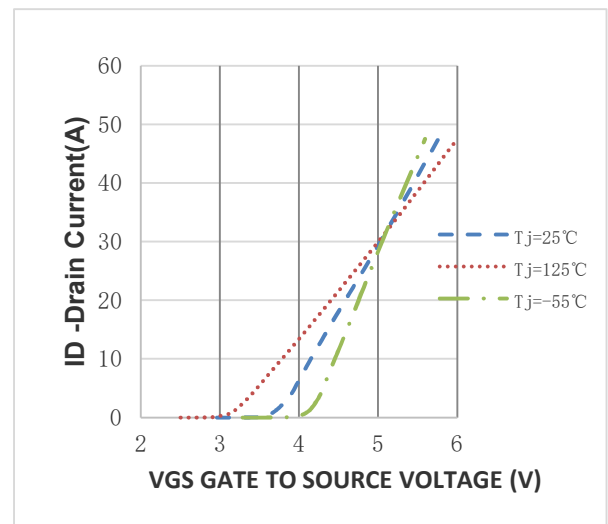


Fig.11 Safe Operating Area

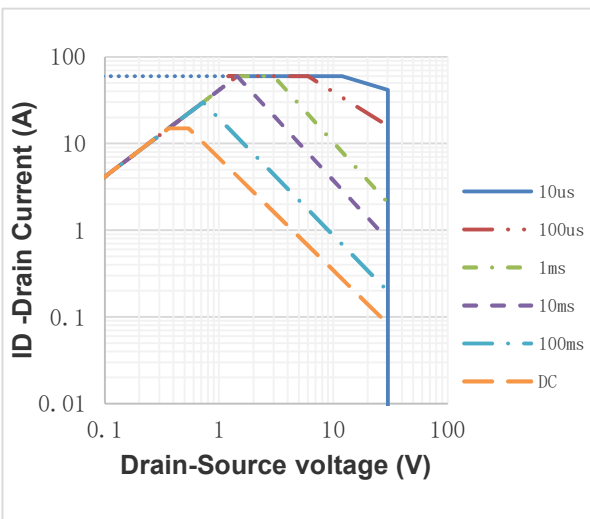
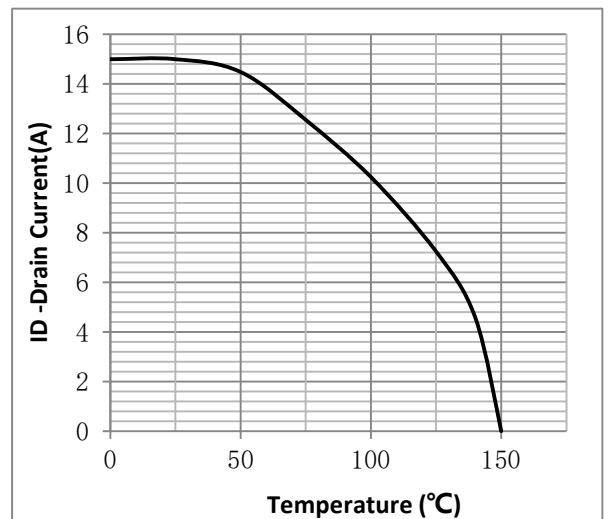
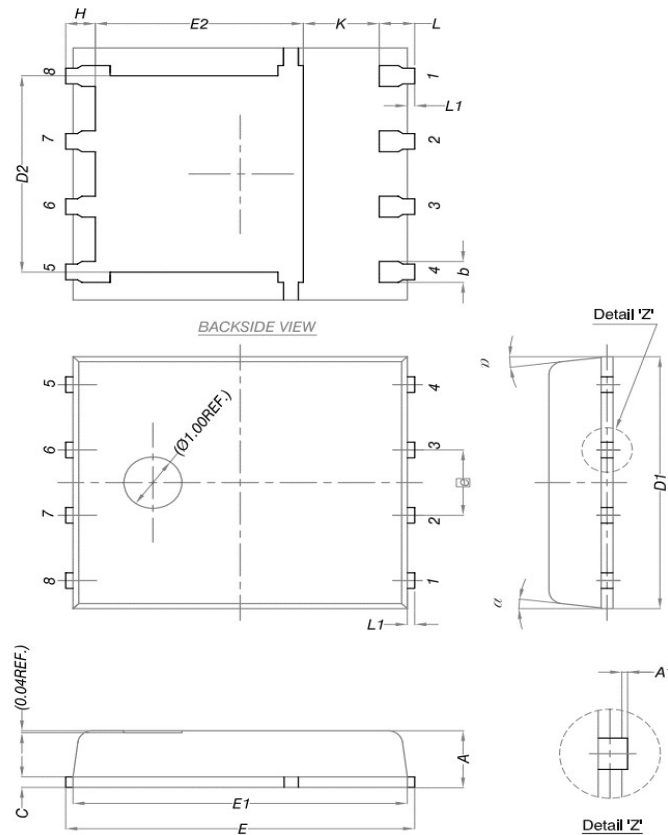


Fig.12 ID vs. Case Temperature^②





•DFN3*3 Package Outline



DIM.	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0	-	0.05
b	0.33	0.41	0.51
C	0.20	0.25	0.30
D1	4.80	4.90	5.00
D2	3.61	3.81	3.96
E	5.90	6.00	6.10
E1	5.70	5.75	5.80
E2	3.38	3.58	3.78
$\square e$	1.27 BSC		
H	0.41	0.51	0.61
K	1.10	-	-
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
α	0°	-	12°

Note:

①Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate;

②Practically the current will be limited by PCB, thermal design and operating temperature. $V_{GS} = -10V$.

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Revision History

Version	Date	Change
A	2020.3.10	NEW
B	2022.10.30	Add ESD level
C	2023.12.28	1.Add dynamic characteristics 2.Fig1~12 modify
D	2024.5.14	Correct Cxss and Qg value